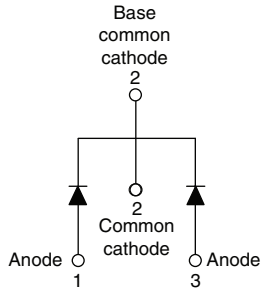
HEXFRED®
Ultrafast Soft Recovery Diode, 2 x 8 A



TO-220AB

FEATURES

- Ultrafast recovery
- Ultrasoft recovery
- Very low I_{RRM}
- Very low Q_{rr}
- Specified at operating conditions
- Designed and qualified for industrial level

BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

HFA16TA60C is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 8 A per leg continuous current, the HFA16TA60C is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to "snap-off" during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED HFA16TA60C is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

PRODUCT SUMMARY	
V_R	600 V
V_F at 8 A at 25 °C	1.7 V
$I_{F(AV)}$	2 x 8 A
t_{rr} (typical)	18 ns
T_J (maximum)	150 °C
Q_{rr}	65 nC
$dI_{(rec)M}/dt$	240 A/µs

ABSOLUTE MAXIMUM RATINGS					
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage		V_R		600	V
Maximum continuous forward current	per leg	I_F	T_C = 100 °C	8	A
	per device			16	
Single pulse forward current		I_{FSM}		60	
Maximum repetitive forward current		I_{FRM}		24	
Maximum power dissipation		P_D	T_C = 25 °C	36	W
			T_C = 100 °C	14	
Operating junction and storage temperature range		T_J, T_{Stg}		- 55 to + 150	°C

ELECTRICAL SPECIFICATIONS PER LEG (T_J = 25 °C unless otherwise specified)							
PARAMETER	**SYMBOL**	**TEST CONDITIONS**		**MIN.**	**TYP.**	**MAX.**	**UNITS**
Cathode to anode breakdown voltage	V_{BR}	I_R = 100 µA		600	-	-	V
Maximum forward voltage	V_{FM}	I_F = 8 A	See fig. 1	-	1.4	1.7	
		I_F = 16 A		-	1.7	2.1	
		I_F = 8 A, T_J = 125 °C		-	1.4	1.7	
Maximum reverse leakage current	I_{RM}	$V_R = V_R$ rated	See fig. 2	-	0.3	5.0	µA
		T_J = 125 °C, V_R = 0.8 x V_R rated		-	100	500	
Junction capacitance	C_T	V_R = 200 V	See fig. 3	-	10	25	pF
Series inductance	L_S	Measured lead to lead 5 mm from package body		-	8.0	-	nH

DYNAMIC RECOVERY CHARACTERISTICS PER LEG (T_J = 25 °C unless otherwise specified)							
PARAMETER	**SYMBOL**	**TEST CONDITIONS**		**MIN.**	**TYP.**	**MAX.**	**UNITS**
Reverse recovery time See fig. 5 and 10	t_{rr}	I_F = 1.0 A, dI_F/dt = 200 A/µs, V_R = 30 V		-	18	-	ns
	t_{rr1}	T_J = 25 °C	I_F = 8.0 A dI_F/dt = 200 A/µs V_R = 200 V	-	37	55	
	t_{rr2}	T_J = 125 °C		-	55	90	
Peak recovery current See fig. 6	I_{RRM1}	T_J = 25 °C		-	3.5	5.0	A
	I_{RRM2}	T_J = 125 °C		-	4.5	8.0	
Reverse recovery charge See fig. 7	Q_{rr1}	T_J = 25 °C		-	65	138	nC
	Q_{rr2}	T_J = 125 °C		-	124	360	
Peak rate of fall recovery current during t_b See fig. 8	$dI_{(rec)M}/dt1$	T_J = 25 °C		-	240	-	A/µs
	$dI_{(rec)M}/dt2$	T_J = 125 °C		-	210	-	

THERMAL - MECHANICAL SPECIFICATIONS PER LEG						
PARAMETER	**SYMBOL**	**TEST CONDITIONS**	**MIN.**	**TYP.**	**MAX.**	**UNITS**
Lead temperature	T_{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C
Junction to case, single leg conducting	R_{thJC}		-	-	3.5	K/W
Junction to case, both legs conducting			-	-	1.75	
Thermal resistance, junction to ambient	R_{thJA}	Typical socket mount	-	-	80	
Thermal resistance, case to heatsink	R_{thCS}	Mounting surface, flat, smooth and greased	-	0.5	-	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-220AB	HFA16TA60C			

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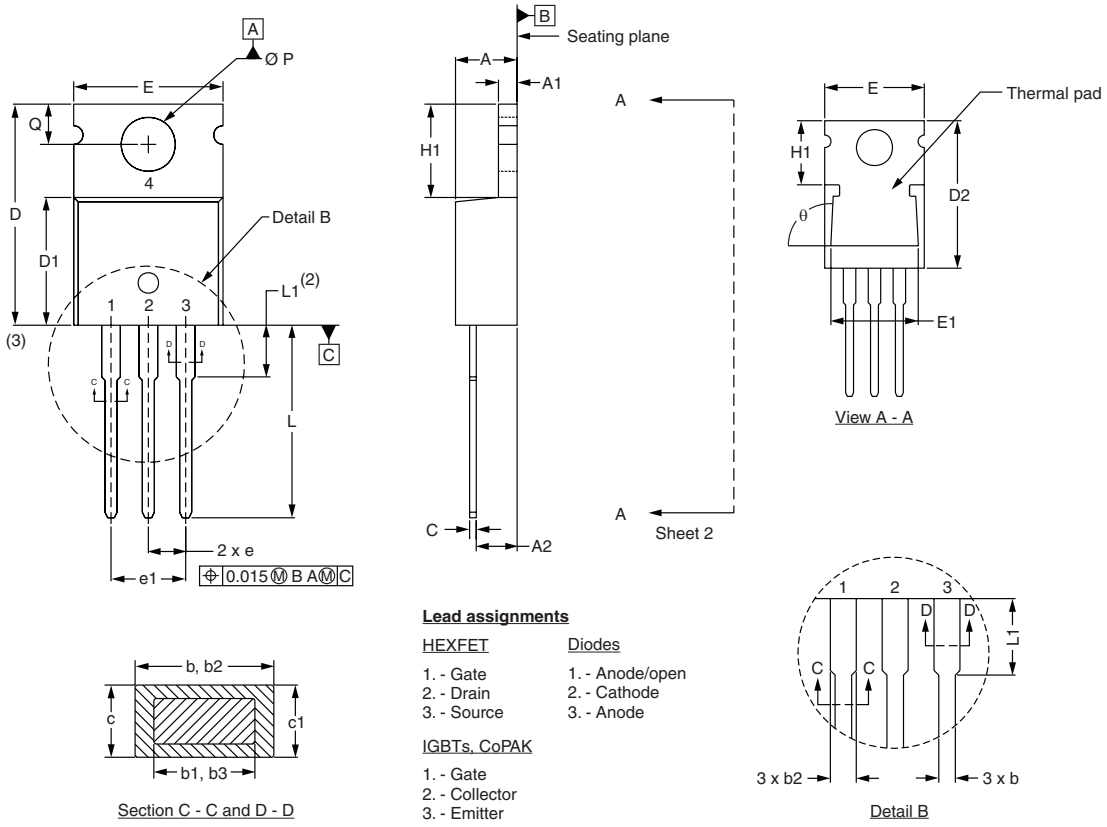
DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	3.56	4.82	0.140	0.190	
A1	0.51	1.40	0.020	0.055	
A2	2.04	2.92	0.080	0.115	
b	0.38	1.01	0.015	0.040	
b1	0.38	0.96	0.015	0.038	4
b2	1.15	1.77	0.045	0.070	
b3	1.15	1.73	0.045	0.068	
c	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
c2	0.31	1.14	0.012	0.045	
D	14.22	15.87	0.560	0.625	3

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	8.38	9.02	0.330	0.355	
D2	12.19	12.88	0.480	0.507	
E	9.66	10.66	0.380	0.420	3
E1	8.38	8.89	0.330	0.350	
e	2.54 BSC		0.100 BSC		
H1	5.85	6.86	0.230	0.270	
L	12.70	14.73	0.500	0.580	
L1	-	6.35	-	0.250	2
Ø P	3.54	3.73	0.139	0.147	
Q	2.54	3.05	0.100	0.120	
θ	90° to 93°		90° to 93°		

Notes

(1) Dimensioning and tolerancing per ASME Y14.5M-1994

(2) Lead dimension and finish uncontrolled in L1

(3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

(4) Dimension b1 and c1 apply to base metal only

(5) Controlling dimensions: inches